

Ultra Low Capacitance Array for ESD Protection

### Description

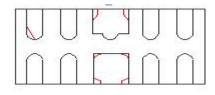
The TQELN7115V0 provides a typical line to line capacitance of 0.3pF between I/O pins and low insertion loss up to 3GHz providing greater signal integrity making it ideally suited for HDMI applications, such as Digital TVs, DVD players, Computing, set-top boxes and MDDI applications in mobile computing devices.

It has been specifically designed to protect sensitive components which are connected to high-speed data and transmission lines from overvoltage caused by ESD(electrostatic discharge), CDE (Cable Discharge Events), and EFT (electrical fast transients).

### • Feature

- 45W peak pulse power (tP = 8/20µs)
- DFN2510 Package
- Working voltage: 5V
- Low clamping voltage
- Low capacitance
- RoHS compliant transient protection for high speed data
- IEC61000-4-2(ESD)±25kV(air),±25kV(contact)

• PIN configuration



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### DFN2510-10L

### • Applications

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- > DVI & HDMI Port Protection
- Serial and Parallel Ports
- Projection TV
- > Notebooks, Desktops, Server
- USB 1.1/2.0/3.0/3.1/OTG

### Machanical data

- Lead finish:100% matte Sn(Tin)
- Mounting position: Any
- Qualified max reflow temperature:260°C
- Device meets MSL 1 requirements
- Pure tin plating: 7 ~ 17 um
- ➢ Pin flatness:≤3mil

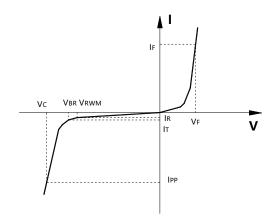
### **Ordering Information**

Device	Package	Marking	Qty per Reel	Reel Size
TQELN7115V0	DFN2510	0524P	3000	7 Inch



## • Electronic Parameter

Symbol	Parameter		
V <sub>RWM</sub>	Peak Reverse Working Voltage		
I <sub>R</sub>	Reverse Leakage Current @ V <sub>RWM</sub>		
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub>		
Ι <sub>Τ</sub>	Test Current		
IPP	Maximum Reverse Peak Pulse		
	Current		
Vc	Clamping Voltage @ IPP		
P <sub>PP</sub>	Peak Pulse Power		
С	Junction Capacitance		



# • Absolute maximum rating @TA=25°C

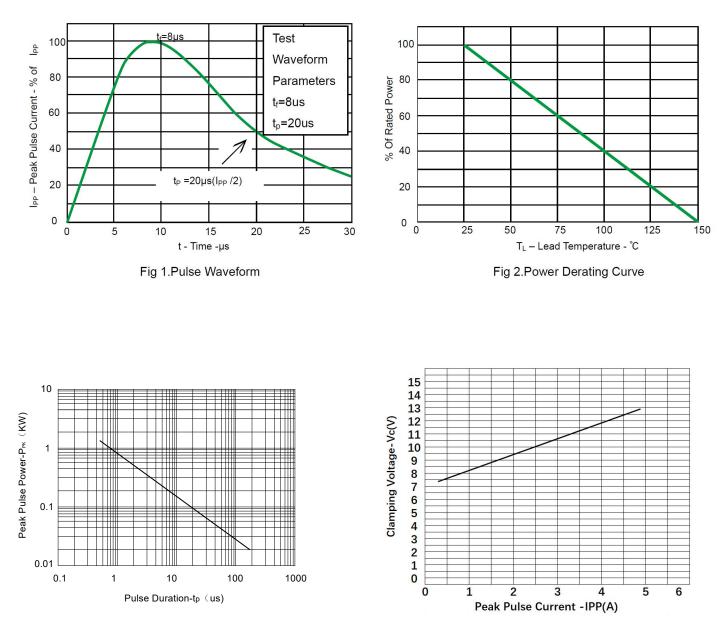
Symbol	Parameter	Value	Units
P <sub>PP</sub>	Peak Pulse Power (8/20µS)	45	W
T <sub>STG</sub>	Storage Temperature	-55/+150	°C
TJ	Operating Temperature	-55/+150	°C

# • Electrical Characteristics @TA=25°C

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Peak Reverse Working	VRWM	Any I/O to Ground		5		V
Voltage						
Brookdown Voltago	M	lt = 1mA	6	0		V
Breakdown Voltage	V <sub>BR</sub>	Any I/O to Ground				
Reverse Leakage Current	I <sub>R</sub>	VRWM =5.0V, T=25°C			1	μA
Diode Forward Voltage	VF	IF = 15mA		0.85	1.2	
Clamping Voltage	Vc	IPP =1A, tP = 8/20µs		8.7		V
Clamping Voltage	Vc	IPP=3.4A, tP = 8/20µs		11.7		V
Junction Capacitance	C, be	VR = 0V, f = 1MHz,		0.25	0.3	pF
		between I/O pins				
		VR = 0V, f = 1MHz,		0.3	0.5	ъF
		any I/O pin to Ground	0.5	0.5		pF

• Typical Performance Characteristics





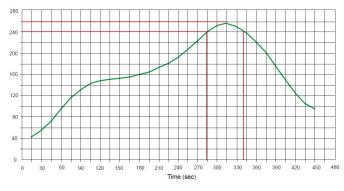
Non-Repetitive Peak Pulse Power vs. Pulse Time

**Clamping Voltage vs Peak Pulse Current** 

• Solder Reflow Recommendation



#### Peak Temp=257°C, Ramp Rate=0.802deg. °C/sec

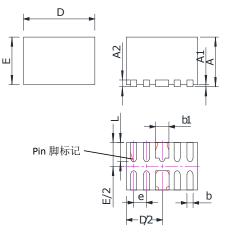


Package Information

## **Mechanical Data**

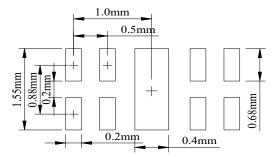
Case:DFN2510

Case Material: Molded Plastic. UL Flammability



DIM	Millimeters		
	Min	Max	
А	0.45	0.65	
A1	0.05REF		
A2	0.15REF		
b	0.15	0.25	
b1	0.30	0.50	
D	2.424	2.576	
E	0.924	1.076	
е	0.50REF		
L	0.30	0.45	

### **Recommended Pad outline**



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